

## A M E N D M E N T S   T O   T H E   C L A I M S

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently amended) An apparatus comprising:

a pre-formed portion of underfill material defining openings, the openings to pass electrical interconnects ~~for coupling~~ formed on a portion of a substrate,

wherein the electrical interconnects are to couple an integrated circuit die to the portion of the substrate.

2. (Currently amended) An apparatus according to Claim 1, further comprising:

a second pre-formed portion of underfill material coupled to the portion of underfill material, the second portion of underfill material defining second openings, the second openings to pass second electrical interconnects formed on a second portion of the substrate,

wherein the second electrical interconnects are to couple ~~for coupling~~ a second integrated circuit die to a the second portion of a substrate.

3. (Original) An apparatus according to Claim 2, further comprising a pre-formed sheet of underfill material comprising the first portion and the second portion.

4. (Original) An apparatus according to Claim 2, further comprising a pre-formed tape of underfill material comprising the first portion and the second portion.

5. (Original) An apparatus according to Claim 1, further comprising:  
the portion of the substrate.

6. (Original) An apparatus according to Claim 5, further comprising:  
the integrated circuit die.

7. (Original) An apparatus according to Claim 1, further comprising:  
the integrated circuit die.

8. (Original) An apparatus according to Claim 1, the underfill material comprising:  
no-flow underfill material.

9. (Withdrawn) A method comprising:  
manufacturing a pre-formed portion of underfill material defining openings, the openings  
to pass electrical interconnects for coupling an integrated circuit die to a portion of a substrate.

10. (Withdrawn) A method according to Claim 9, wherein manufacturing the portion  
comprises:

pressing the underfill material against a template of the openings to create the openings.

11. (Withdrawn) A method according to Claim 10, wherein manufacturing the portion  
further comprises:

plasma etching the openings to further create the openings.

12. (Withdrawn) A method according to Claim 9, further comprising:  
attaching the underfill material to the substrate.

13. (Withdrawn) A method according to Claim 12, further comprising:

coupling the substrate to the integrated circuit die using electrical interconnects passing through the openings.

14. (Currently amended) A system comprising:

a microprocessor comprising:

an integrated circuit die;

a substrate;

a plurality of electrical interconnects formed on the substrate and coupling the integrated circuit die to the substrate; and

a pre-formed portion of underfill material pre-formed to define openings, the openings passing the plurality of electrical interconnects ~~for coupling the integrated circuit die to the substrate~~; and

a double data rate memory coupled to the microprocessor.

15. (Original) A system according to Claim 14, the underfill material comprising:

no-flow underfill material.

16. (Currently amended) A system according to Claim 14,

the integrated circuit die comprising a first plurality of electrical contacts;

~~the substrate comprising a second plurality of electrical contacts; and~~

~~the electrical interconnects for coupling the first plurality of electrical contacts to the second plurality of electrical contacts~~substrate.